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**M24512-DF package mechanical data modifications**

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**Silicon identification**

This errata sheet applies to the M24512-DF, which is 512Kbit serial I<sup>2</sup>C bus EEPROMs, and specifically to the device delivered in 8-bump wafer-level chip-scale packages (WLCSP).

[Table 1](#) shows the list of part numbers.

**Table 1. Device summary**

Reference	Part Number
M24512-DF	M24512-DFCS6TP/K

# Contents

<b>1</b>	<b>M24512-DF physical product change .....</b>	<b>5</b>
<b>2</b>	<b>Package mechanical data modifications .....</b>	<b>8</b>
<b>3</b>	<b>Revision history .....</b>	<b>9</b>

## List of tables

Table 1.	Device summary . . . . .	1
Table 2.	D and E values corresponding to front side view . . . . .	8
Table 3.	D and E values corresponding to back side view . . . . .	8
Table 4.	Document revision history . . . . .	9

## List of figures

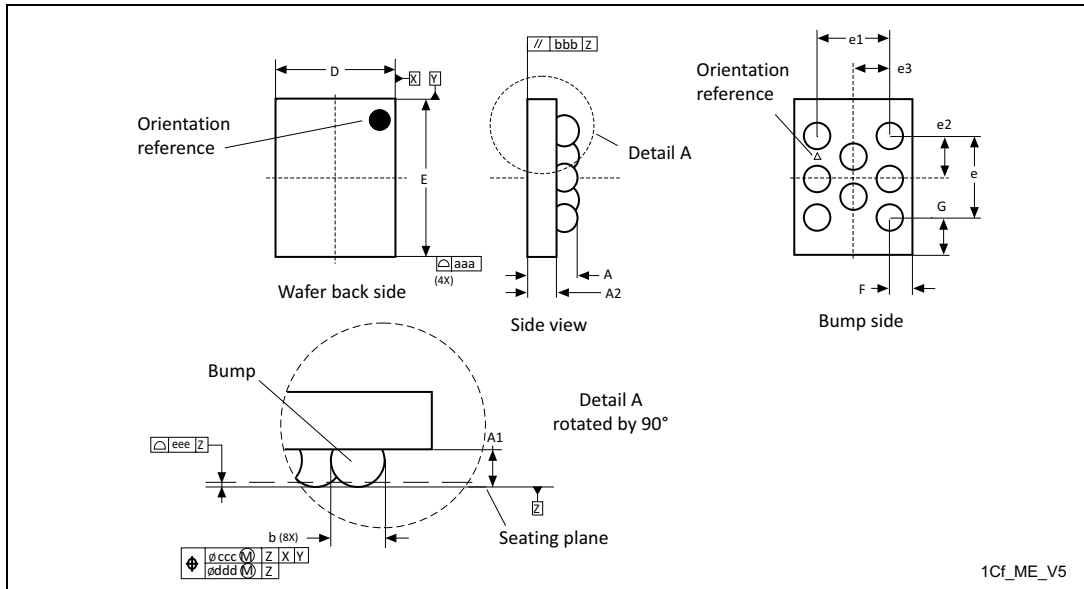
Figure 1.	WLCSP 8-bump, 1.271 x 1.937 mm, 0.5 mm pitch wafer level chip scale package outline . . . . .	5
Figure 2.	D and E front side view . . . . .	6
Figure 3.	D and E back side view . . . . .	6
Figure 4.	D or E side view . . . . .	7

# 1 M24512-DF physical product change

There is not any physical product change.

*Figure 1* shows the package outline.

**Figure 1. WLCSP 8-bump, 1.271 x 1.937 mm, 0.5 mm pitch wafer level chip scale package outline**



The figures below show the difference between  $D$  and  $E$  dimensions in the front side view (see *Figure 2*), back side view (see *Figure 3*) and side view (see *Figure 4*).

Figure 2. D and E front side view

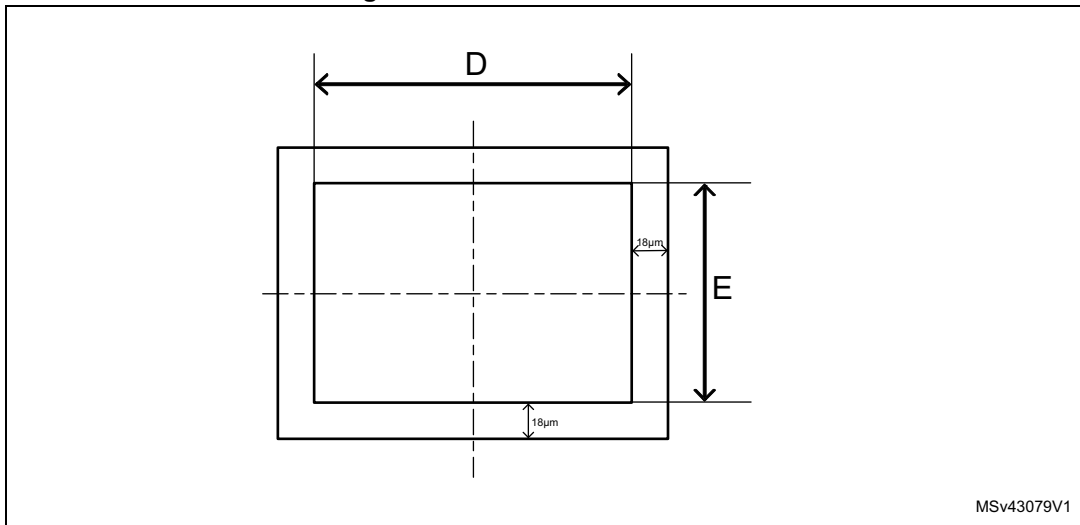


Figure 3. D and E back side view

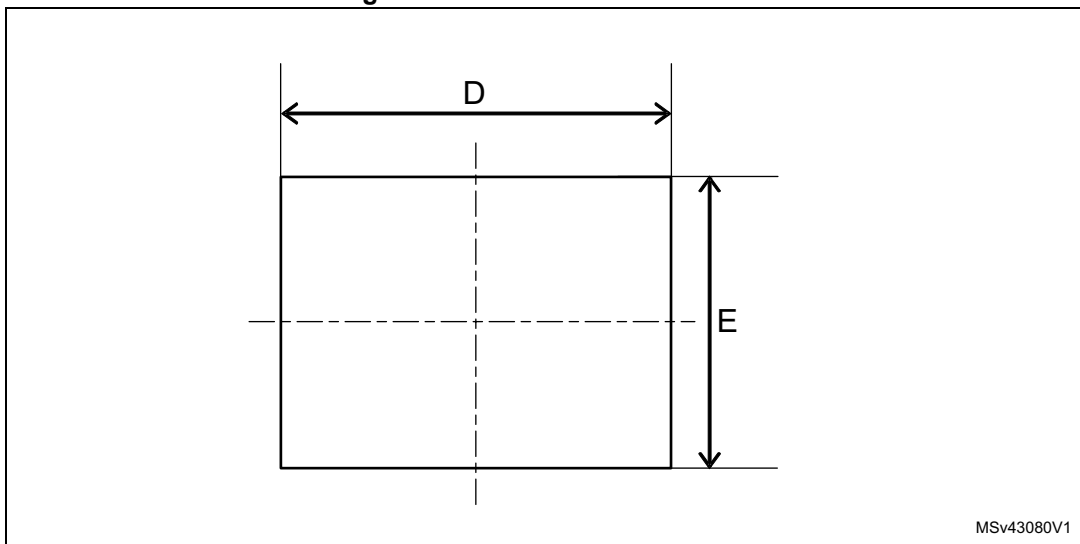
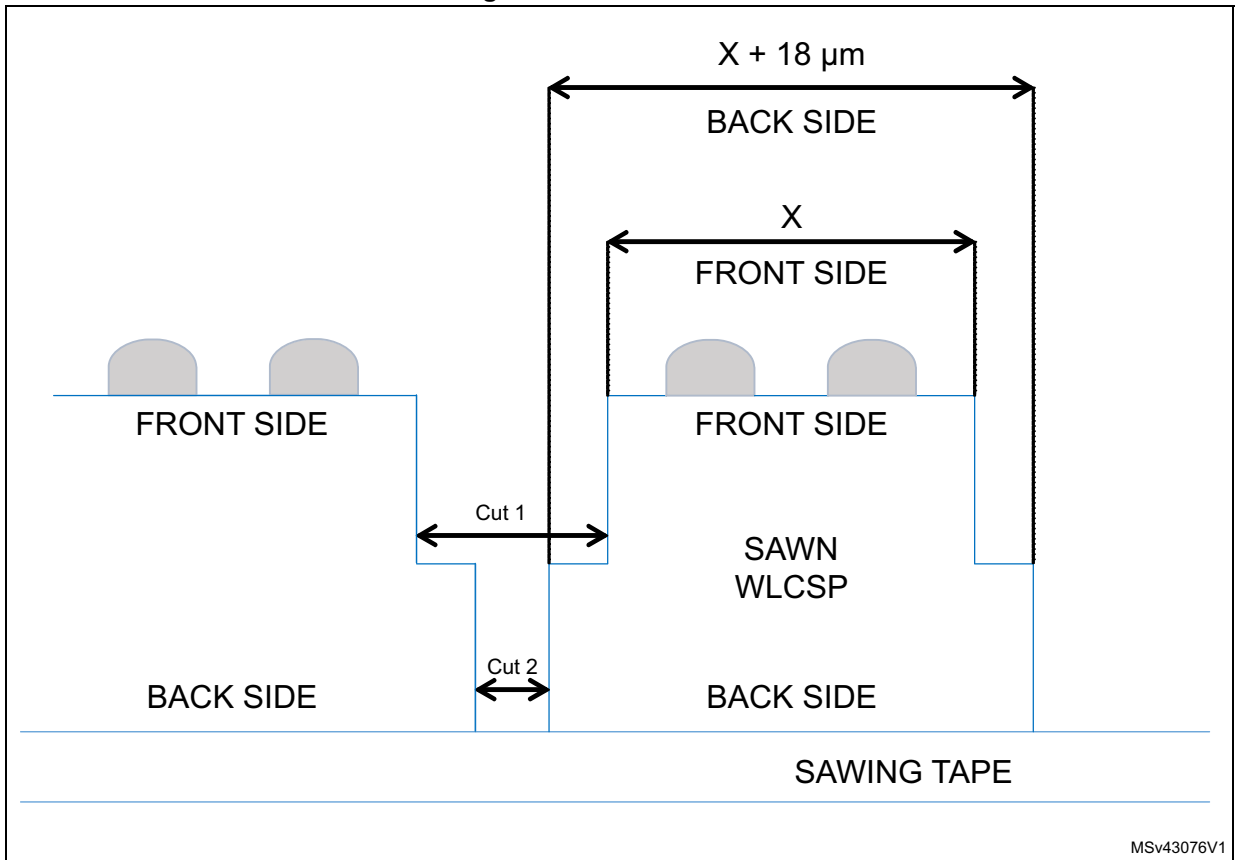


Figure 4. D or E side view



## 2 Package mechanical data modifications

This document refers to the changes in dimensions D and E (see [Figure 3](#)) described in the M24512-DF datasheet, in tables detailing the dimensions of the WLCSP 8-bump package.

D and E values must be modified to correct the following mistake:

- The D and E values in the M24512-DF datasheet correspond to front side view (ball side), instead of back side view (marking side view).  
[Table 2](#) and [Table 3](#) report the data for the front and back view, respectively.

**Table 2. D and E values corresponding to front side view**

Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
D	-	1.271	1.291	-	0.0500	0.0508
E	-	1.937	1.957	-	0.0763	0.0770

**Table 3. D and E values corresponding to back side view**

Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
D	-	1.289	1.309	-	0.0507	0.0515
E	-	1.955	1.975	-	0.0770	0.0778

The difference between back side and front side dimension is 18 µm (0.018 mm). This difference is due to the two-step sawing process, where cut 1 and cut 2 are performed with blades having different thicknesses (see [Figure 4](#) in which X represents D or E and it has the same value and tolerance).



### 3 Revision history

Table 4. Document revision history

Date	Revision	Changes
19-Oct-2018	1	Initial release.

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